### 400 mil DIP8

# **Mechanical and Environmental Testing**



## **Reliability Data Sheet**

#### **Description**

This document's reliability data includes Broadcom reliability test data from the reliability tests done on this product family. All of these products use similar processes and materials. The data in Table 1 and Table 2 reflects actual test data for devices. Before stress, all devices are preconditioned at MSL 1 using a solder reflow process (260°C peak temperature) and 20 temperature cycles (–55°C to +125°C, 15 minutes dwell, 1 minute transfer). This data is taken from testing on Broadcom devices using internal Broadcom processes, material specifications, design standards, and statistical process controls

They are not transferable to other manufacturers' similar part types.

#### **Definition of Failure**

Abnormal resistance, that is, "open or short failure", is the definition of failure in this data sheet. Specifically, failure occurs when the device fails contact resistance either high or low, when the device experiences abnormal leakage, or both.

#### **Reliability Testing**

Broadcom subjects the devices to a series of reliability tests, including environmental, mechanical, and electrical tests, to ensure that the product meets the intended reliability expectations. The tables provided in his data sheet show the results of reliability testing conducted by Broadcom over a period of time as shown in the test conditions.

Table 1 Mechanical Tests (Testing Done on a Constructional Basis)

| Test Name           | Reference<br>Standard | Test Conditions  | Units Tested | Units Failed |
|---------------------|-----------------------|--|--------------|--------------|
| Temperature Cycling | JESD-A104             | -55°C to 125°C, Transfer = 1 min, Dwell = 15 mins, 1000 cycles | 2279         | 0            |
| J                   | JESD-020<br>JESD-A113 | As per reference standard (to conform to MSL 1)                | 2827         | 0            |

Table 2 Environmental Tests (Testing Done on a Constructional Basis

| Test Name  | Reference<br>Standard | Test Conditions   | Units Tested | Units Failed |
|--|-----------------------|---|--------------|--------------|
| Temperature-Humidity-Bias                          | JESD-A101             | T <sub>A</sub> = 85°C, RH=85%, Biased, Time = 1000 hrs    | 1174         | 0            |
| Highly Accelerated Stress Test (HAST)              | JESD-A110             | T <sub>A</sub> = 130°C, RH =85%, Unbiased, Time = 96 hrs  | 221          | 0            |
| Unbiased Highly Accelerated Stress<br>Test (uHAST) | JESD-A118             | T <sub>A</sub> = 130°C, RH =85%, Unbiased, Time = 96 hrs  | 462          | 0            |
| Autoclave  | JESD-A102             | T <sub>A</sub> = 121°C, RH =100%, Unbiased, Time = 96 hrs | 560          | 0            |
| High Temperature Bake                              | JESD-A103             | T <sub>A</sub> = 150°C, Unbiased, Time = 1000hrs          | 461          | 0            |

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